



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-24
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA75612LV-48X	H848*UK82AB6	A	SH1A	2013-10-24
Amount		UoM	Unit type	ST ECOPACK Grade
7108.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SMD	15.7x29.23x4.5	27	NAC
Comment			

Material Composition Declaration						Mfr Item Name	H848*UK82AB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	25.010	mg	supplier	die	Silicon (Si)	7440-21-3		23.912	mg	956098	3364
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.157	mg	6277	22
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.157	mg	6277	22
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.191	mg	7637	27
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.038	mg	1519	5
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.368	mg	14714	52
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.014	mg	560	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.036	mg	1439	5
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.122	mg	4878	17
die (s)				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.015	mg	600	2
Leadframe	Copper & its alloys	5212.858	mg	supplier	alloy	Copper (Cu)	7440-50-8		5203.060	mg	998120	732001
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		2.397	mg	460	337
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		4.376	mg	839	616
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.025	mg	580	426
Die attach		14.077	mg	JIG Table A	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	13.725	mg	974995	1931
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.211	mg	14989	30
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.141	mg	10016	20
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		5.379	mg	1000000	757
encapsulation		1812.092	mg	supplier	mold compound	Amorphous Silica	7631-86-9		1540.277	mg	849999	216696
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		108.725	mg	60000	15296
encapsulation				supplier	mold compound	epoxy resin	na		72.484	mg	40000	10198
encapsulation				supplier	mold compound	Phenol resin	na		72.484	mg	40000	10198
encapsulation				supplier	mold compound	Carbon black	1333-86-4		12.685	mg	7000	1785
encapsulation				JIG table B	mold compound	Bismuth (Bi)	7440-69-9		5.437	mg	3000	765
connections coating	Solder	38.585	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		38.585	mg	1000000	5428